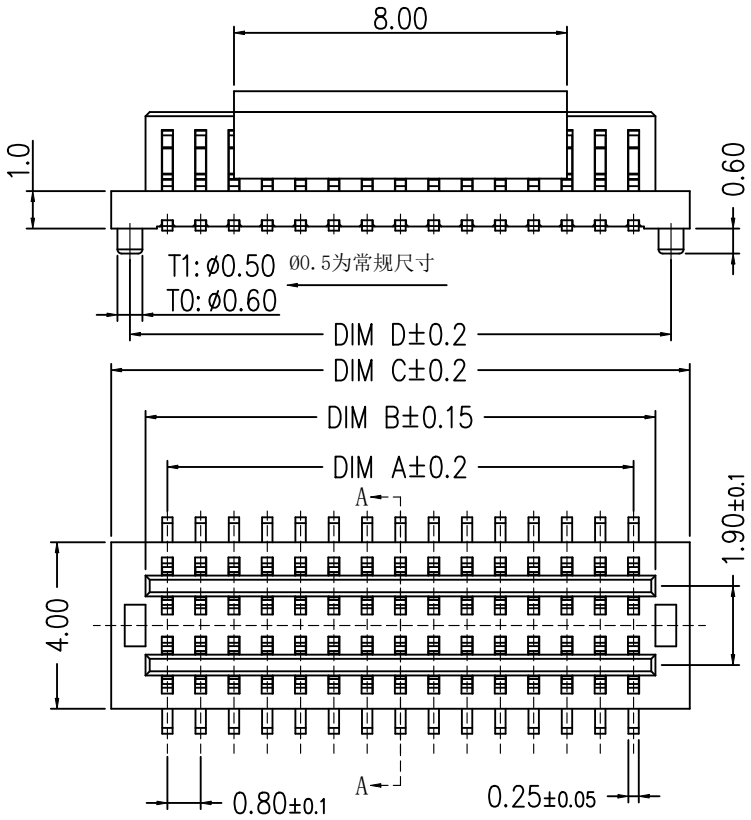
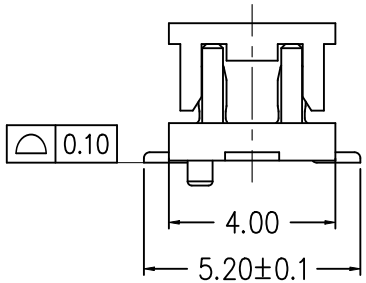
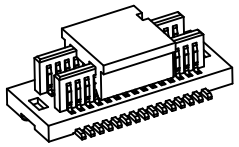
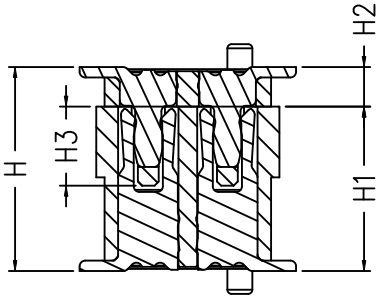
版次	变更摘要	日期
0	新产品发行	2023.4.26
1	料号更新	2024/12/14

序号	品名	材质
①	0.8 Pitch双槽立式BTB公座胶芯	PA10T UL94 V-0,颜色:黑色
②	0.8 Pitch双槽立式BTB公座端子	铜合金/表面镀锡
③	0.8 Pitch双槽立式BTB公座吸盖	LCP UL94 V-0,颜色:黑色

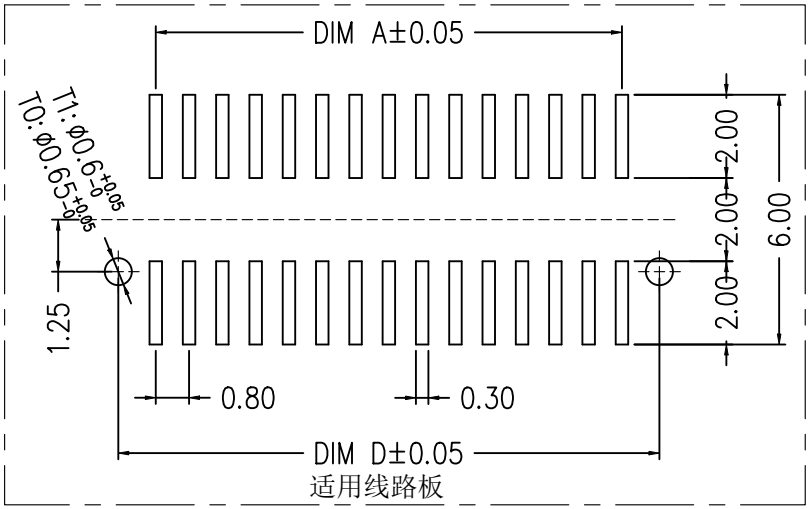








High photosynthesis 合高(H)	The female seat neight 母座单高(H1)	The male seat neight 公座单高(H2)	Insertion height (H3)
4.0	3.0	1.0	1.9
4.5	3.5	1.0	1.9
5.0	3.0/4.0	2.0/1.0	1.9
5.5	3.5/4.5	2.0/1.0	1.9
6.0	4.0	2.0	1.9
6.5	4.5	2.0	1.9
7.0	3.0	4.0	1.9
7.5	3.5	4.0	1.9
8.0	4.0	4.0	1.9
8.5	4.5	4.0	1.9



CKT	DIM A	DIM B	DIM C	DIM D	DIM D
8	2.40	3.45	5.10	4.20	4.00
10	3.20	4.25	5.90	5.00	
12	4.00	5.05	6.70	5.80	
14	4.80	5.85	7.50	6.60	
16	5.60	6.65	8.30	7.40	
18	6.40	7.45	9.10	8.20	
20	7.20	8.25	9.90	9.00	
22	8.00	9.05	10.70	9.80	
24	8.80	9.85	11.50	10.60	8.00
26	9.60	10.65	12.30	11.40	
28	10.40	11.45	13.10	12.20	
30	11.20	12.25	13.90	13.00	
32	12.00	13.05	14.70	13.80	
34	12.80	13.85	15.50	14.60	
36	13.60	14.65	16.30	15.40	
38	14.40	15.45	17.10	16.20	
40	15.20	16.25	17.90	17.00	
44	16.80	17.85	19.50	18.60	
50	19.20	20.25	21.90	21.00	
60	23.20	24.25	25.90	25.00	
70	27.20	28.25	29.90	29.00	
80	31.20	32.25	33.90	33.00	
100	39.20	40.25	41.90	41.00	

技术指标:

1. 塑件表面应光洁、无毛边、无明显收缩、缺陷、裂纹等现象.
2. 温度范围：-40° C～85° C.
3. 额定电压：125V，AC.
4. 接触电阻：≤0.02Ω.
5. 绝缘电阻:≥100MΩ
6. 产品料号：

BB0800100M—*** * *—***

- NO OF CKT(产品PIN数)
- Plating(电镀方式)
  - 0:端子全雾锡
  - 1:端子镀全金（Gold Flash）
  - 2:端子点镀金
  - 4:端子半金锡
  - 9:未镀(None)
- Packing(包装方式)
  - R:TAPE & REEL卷装
  - C:TAPE & REEL WITH COVER 加吸盖卷装
- 流水码

一般公差(TOLERANCE)
X. ±.50 .XX ±.10
.X ±.20 .XXX ±.05
ANGLES ±1°

ZGWD 浙江温达电子有限公司
ZHEJIANG WENDA ELECTRONICS CO.,LTD

品名 (TITLE) 0.8 Pitch双槽立式BTB公座业务图(单高1.0)		制图 (DR) Anlan	
		校对 (CHKD) 田峰	
料号 (DWG.NO) BB0800100M-*****-***		审核 (APPD) 黄志明	
比例 (SCALE)	单位 (UNITS) mm	张数 (SHEET) 1 OF 1	SIZE A4 / REV A